PCN Number:		20190513000		PCN Date:	May	May 29, 2019		
Title: Datasheet for TS5A2			3157					
<b>Customer Contact:</b> PCN N		PCN M	<u>Manager</u>			Dept:		Quality Services
Change Type:								
Assembly Site				Design			Wafer	Bump Site
Assembly Process		$\boxtimes$	□ Data Sheet			Wafer	Bump Material	
Assembly Materials			Part number change			Wafer	Bump Process	
Mechanical Specification			Test Site			Wafer	Fab Site	
Packing/Shipping/Labeling			9 🔲	Test Process			Wafer	Fab Materials
			•				Wafer	Fab Process
Notification Details								

## **Description of Change:**

Texas Instruments Incorporated is announcing an information only notification.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.



TS5A23157

SCDS165F -MAY 2004-REVISED JANUARY 2019

hanges from Revision A (October 2018) to Revision B	Pag
Changed Features	
Changed From: 51 To: 64 in Features	
Changed From: 50 To: 63 in Features	
Changed From: 300 To: 384 in Features	
Changed From: 51 To: 64 in Description	
Changed Simplified System Diagram	
Changed From: Connect CB1 to VC1 To: Short CB1 to CB0 in CB1 Description in Pin Functions	
Changed From: Connect CB2 to VC2 To: Short CB2 to CB1 in CB2 Description in Pin Functions	
Changed From: Connect CB3 to VC3 To: Short CB3 to CB2 in CB3 Description in Pin Functions	
Changed From: Connect CB4 to VC4 To: Short CB4 to CB3 in CB4 Description in Pin Functions	
Changed From: Connect CB5 to VC5 To: Short CB5 to CB4 in CB5 Description in Pin Functions	
Changed From: Connect CB6 to VC6 To: Short CB6 to CB5 in CB6 Description in Pin Functions	
Changed TSREF TYPE from I to O in Pin Functions	
Changed I <sub>VLDO(LIMIT)</sub> into I <sub>VLDO(LIMIT)LP</sub> and I <sub>VLDO(LIMIT)HP</sub> in Electrical Characteristics	1
Changed Figure 1	
Changed From: 51 (1 base and 50 stack) To: 64 (1 base and 63 stack) in Overview	1
Added sentence to Precision References	2
Changed SYS_FAULT1[POR] to SYS_FAULT1[DRST] in POR (Power On Reset) section	4
Changed From: 51 devices (1 base device and 50 stack devices) To: 64 devices (1 base device and 63 stack devices) in Communication Interfaces and Programming	4
Changed SYS_FAULT1[CTS_FLT] to SYS_FAULT1[CTS] in Short Communications Timeout Fault section	7
Changed 0x200 PARTID Factory OTP Reset Value in Register Summary Table From: 0x04 To: Various	10
Changed 0x27E OTP_CUST1_STAT1 Reset Value in Register Summary Table From: 0x03 To: 0x01	

<ul> <li>Changed 0x27E OTP_CUST1_STAT1 Factory OTP</li> </ul>	Reset Value in Register Summary Table From: 0x03 To: 0x01 105
Changed B1 bit value in Register: OTP_CUST1_ST	AT1 From: 1 To: 0
Changed Figure 43	
Changed Equation 11	
Changed Equation 12	237
Changed Equation 13	237
	248
Changed Figure 59	249
Changed Figure 61	251
	e. from Application Curves
Changed Figure 63	

The datasheet number will be changing.

Device Family	Change From:	Change To:
TS5A23157	SLUSC97A	SLUSC97B

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/TS5A23157

#### **Reason for Change:**

To reflect the device pin descriptions accurately.

### Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

# Changes to product identification resulting from this PCN:

None.

#### **Product Affected:**

TS5A23157DGSR	TS5A23157DGSRE4	TS5A23157DGSRG4	TS5A23157DGST
TS5A23157RSER			

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com